DB2U308

Silicon epitaxial planar type

For high speed switching circuits DB27308 in USSMini2 type package

■ Features

- Low forward voltage V_F
- Short reverse recovery time t_{rr}
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

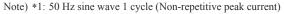
■ Marking Symbol: 11

Packaging

DB2U30800L Embossed type (Thermo-compression sealing): 10 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	30	V	
Repetitive peak reverse voltage	V _{RRM}	30	V	
Forward current (Average)	I _{F(AV)}	100	mA	
Peak forward current	I_{FM}	200	mA	
Non-repetitive peak forward surge current *1	I _{FSM}	1	A	
Junction temperature	T _j	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

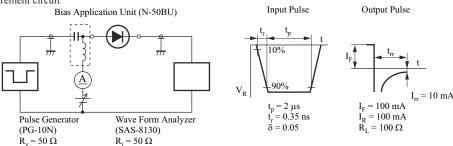


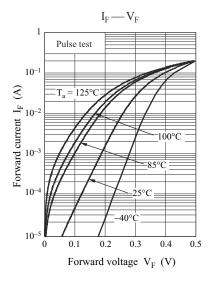
Unit: mm 0. 6 0. 13 0. 2 0. 38 1: Cathode 2: Anode Panasonic USSMini2-F2-B JEITA SC-116A Code SOD-923

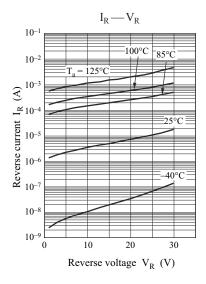
■ Electrical Characteristics $T_a = 25$ °C±3°C

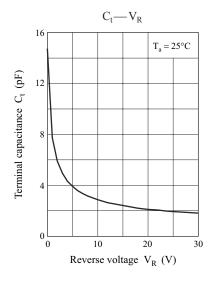
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 10 \text{ mA}$			0.29	V
	V_{F2}	$I_F = 100 \text{ mA}$			0.42	
Reverse current	I_{R1}	$V_R = 10 \text{ V}$			25	μΑ
	I_{R2}	$V_R = 30 \text{ V}$			120	
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2.9		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		1.3		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz
 - *1: t_{rr} measurement circuit





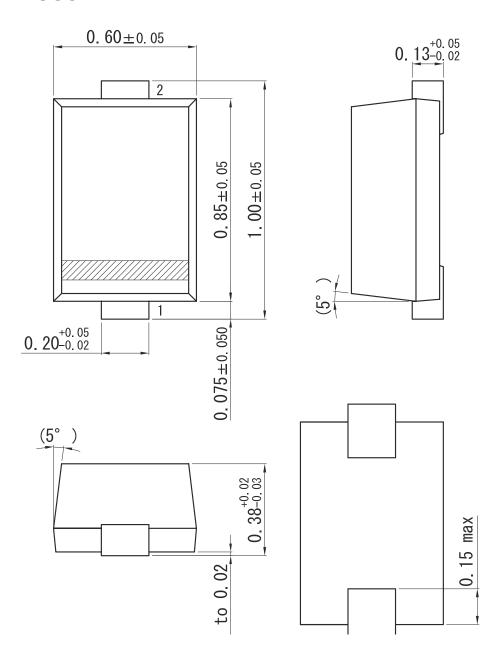




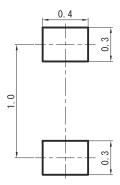
Ver. CED 2

USSMini2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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